Cypress Semiconductor Corporation, 198 Champion Court, San Jose, CA 95134. Tel: (408) 943-2600

PRODUCT CHANGE NOTIFICATION

PCN: PCN154207B **Date:** February 16, 2016

Subject: Addendum to PCN154207A: Qualification of an Alternate Mold Compound and Die Attach Epoxy for Select TSOP I Product

To: TOKYO ELECTRON DEVICE
cy-pcn@teldevice.co.jp

Change Type: Major

Description of Change:
The purpose of this addendum is to correct the implementation from “Effective 90 days from the date of this notification or upon customer approval, whichever comes first,” to “This change will be effective upon customer approval.”

Cypress announced the qualification of an alternate die attach epoxy (Sumitomo CRM-1150B) and mold compound (Sumitomo G600B/SB) for the assembly of select devices manufactured in TSOP I packages assembled at Cypress Bangkok.

The qualification will enable Cypress to continually provide world-class services and meet our customers‟ stringent quality and reliability requirements. TSOP packages assembled at Cypress Bangkok will use the following Bill of Materials (BOM).

TSOP		
	Current	**New**
Die Attach Epoxy	Ablestik 8340	Ablestik 8340 Sumitomo CRM-1150B
Mold Compound	Hitachi CEL 9200HF10 Hitachi CEL 9200HF10-U	Hitachi CEL 9200HF10 Hitachi CEL 9200HF10-U Sumitomo G600B Sumitomo G600SB

There are no changes to ordering part numbers. Product datasheets remain the same and can be downloaded from the Cypress Website (www.cypress.com).

Benefit of Change:
The addition of Sumitomo CRM-1150B die attached epoxy and G600B/G600SB mold compound allows the increase of assembly material availability and flexibility.

Affected Part Numbers: 130

Affected Parts: See the attached „Affected Parts List" file for a list of all part numbers (original and addendum) affected by this change. Note that any new TSOP parts that are introduced after the publication of this PCN may also be manufactured with CRM-1150B die attach epoxy and G600B/G600SB mold compound at the Cypress Bangkok facility.

Qualification Status:

The change has been qualified through a series of tests documented in Qualification Test Plan (QTP) 153704. The qualification report can be found as an attachment to this notification.

Sample Status:

Qualification samples are not built ahead of time for all part numbers affected by this change. Please contact your local Cypress Sales representative for sample availability as soon as possible, but within 30 days of the date of this PCN, to place any sample orders.

Approximate Implementation Date:

This change will be effective upon customer approval.

Anticipated Impact:

Products manufactured with Sumitomo CRM-1150B die attach epoxy and Sumitomo G600B/G600SB mold compound are completely compatible with existing product from a functional, parametric, and quality performance perspective.

Cypress recommends that customers take this opportunity to review these changes against current application notes, system design considerations and customer environment conditions to assess impact (if any) to their application.

Method of Identification:

There will be no changes to the part number. Cypress maintains traceability of product to wafer level, including wafer fabrication location, through the lot number marked on the package.

For additional information regarding this change, contact your local sales representative or contact the PCN Administrator at pcn_adm@cypress.com.

Sincerely,

Cypress PCN Administration